Schematics Drafted in : Allegro Design entry CIS 17.2

REV	Revision Notes	Designer	Approver	Date
A1	First Release	VVDN	TI	17-06-2019
A2	1. R538 Replaced with 300E Resistor 2. C535 Replaced with 4.7uF, 10V Capacitor 3. U37 replaced with TPS3808G25DBVR 4. D34 Made NO MOUNT 5. R660 Made NO MOUNT, R684 Mounted with 0E	VVDN	TI	05-09-2019
B1	1. VDD_3V3 Connected to Q6.2. which connects to VDD of J28. This is for keeping SD card VDD voltage at 3V3. 2. Moved the position of I2C1 signals of Header H1 from pin 9 & 10 to pin 1 & 2. 3. Added Capacitor C578, C579 across SW5 and SW6. 4. PGOOD LED of PMIC connected from PGOOD pin of TPS6521815. 5. PMIC_STBY from uP used for resetting DCDC1 of TPS6521815. 6. PMIC_GPIO1 used for enabling DCDC converters other than TPS6521815.	VVDN	TI	24-10-2019

TIXU_MX7D

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03	MAIN POWER
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10	eMMC/FLASH/SD
11	mini PCIe
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20	CSI/WATCHDOG/IO
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TIDA-050034

TIXU MX7D

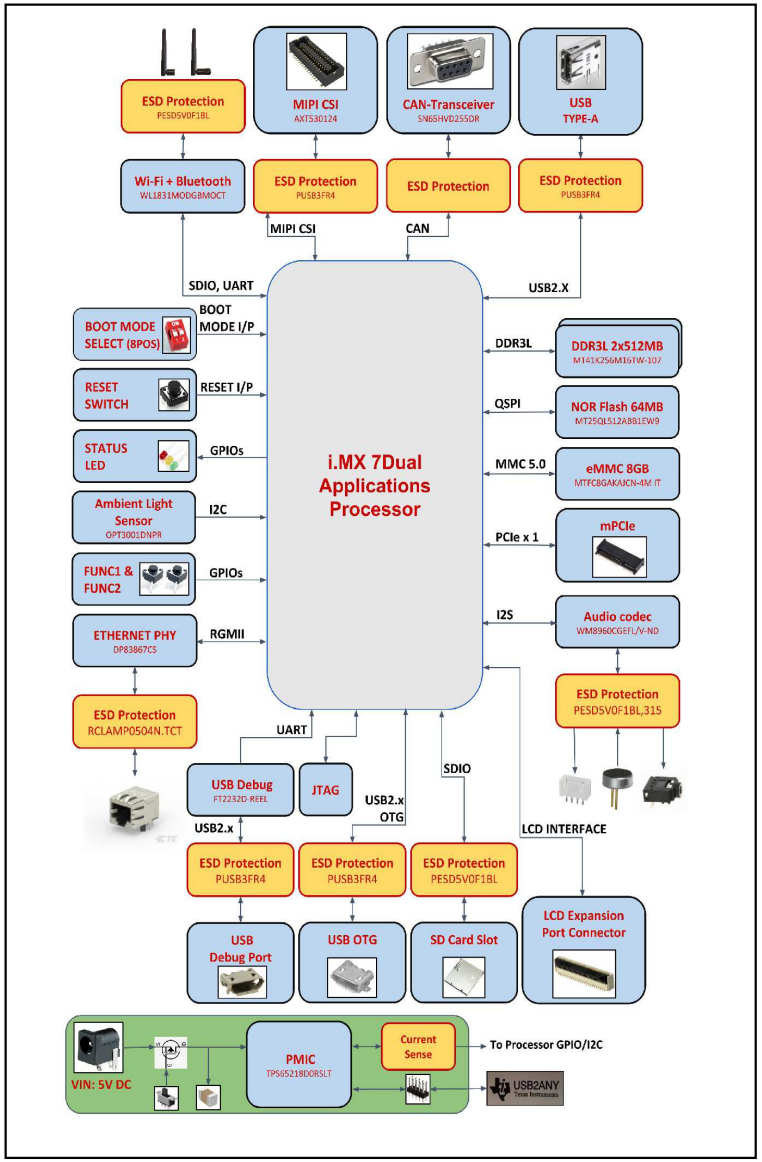
VVDN TECHNOLOGIES

A2 | Title : COVER_PAGE

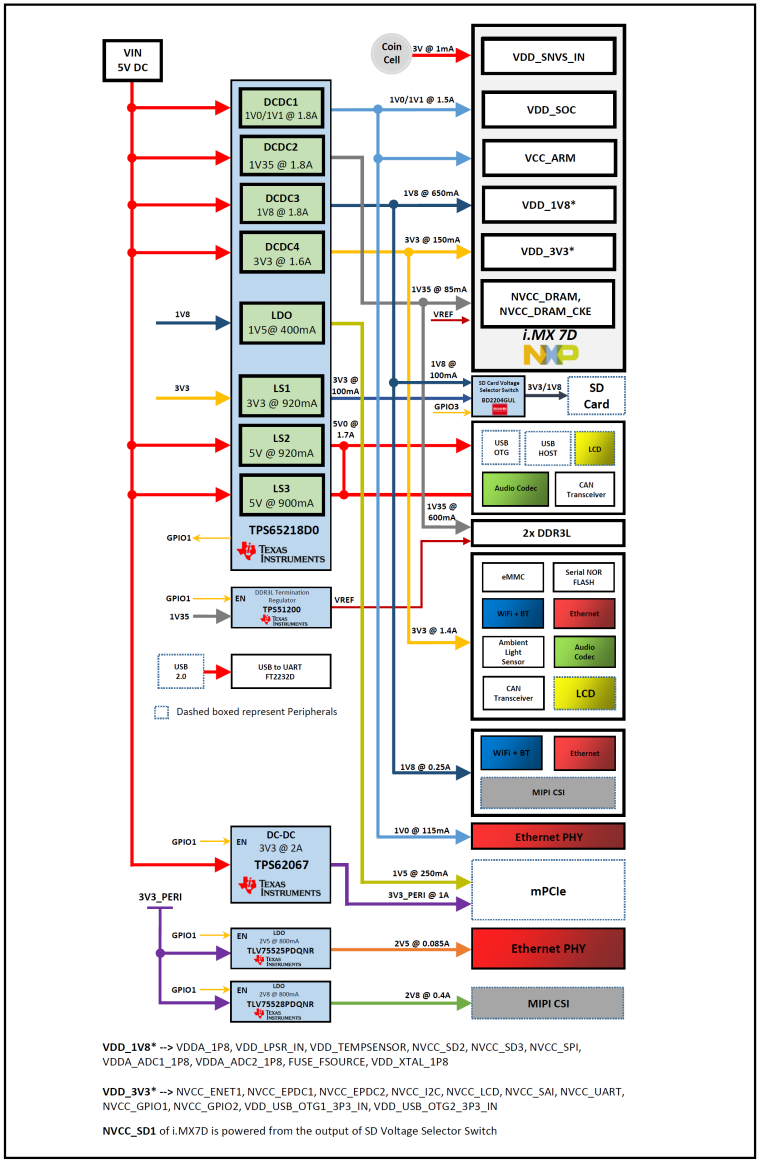
Fab No : 501-1-00947 | Rev: B1

Asy No : 701-1-01125 | Sheet 1 of 21

BLOCK DIAGRAM



POWER ARCHITECTURE



VDD_1V8* --> VDDA_1P8, VDD_LPSR_IN, VDD_TEMPSENSOR, NVCC_SD2, NVCC_SD3, NVCC_SPI, VDDA_ADC1_1P8, VDDA_ADC2_1P8, FUSE_FSOURCE, VDD_XTAL_1P8

VDD_3V3* --> NVCC_ENET1, NVCC_EPDC1, NVCC_EPDC2, NVCC_I2C, NVCC_LCD, NVCC_SAI, NVCC_UART, NVCC_GPIO1, NVCC_GPIO2, VDD_USB_OTG1_3P3_IN, VDD_USB_OTG2_3P3_IN

NVCC_SD1 of i.MX7D is powered from the output of SD Voltage Selector Switch

TIXU MX7D

VVDN TECHNOLOGIES	A2	Title : BLOCK_DIAGRAM
	Fab No : 501-1-00947	Rev: B1
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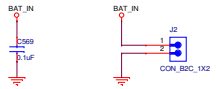
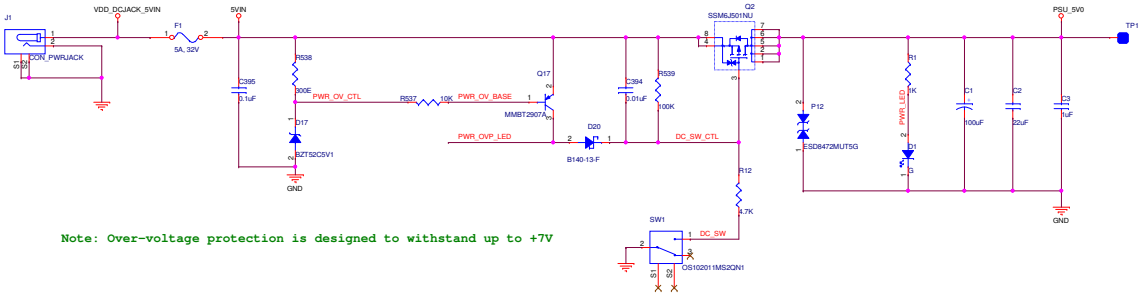
BATTERY IN



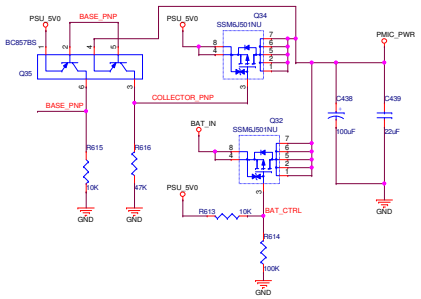
5V DC POWER

OVER VOLTAGE PROTECTION

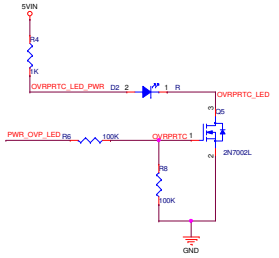


Note: Over-voltage protection is designed to withstand up to +7V

ORING



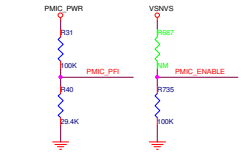
OVER VOLTAGE INDICATOR



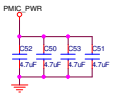
TIXU MX7D

VVDN TECHNOLOGIES	A2	Title : MAIN POWER
	Fab No : 501-1-00947	Rev: B1
	Asy No : 701-1-01125	Sheet 3 of 21

PMIC



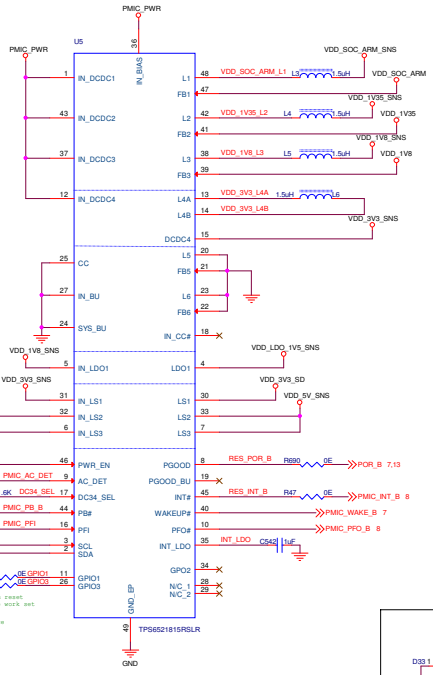
Power failure is notified to system if PMIC_PWR go below 3.52V

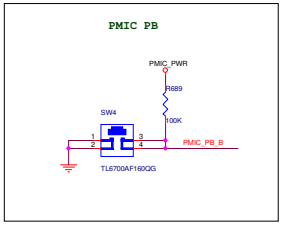


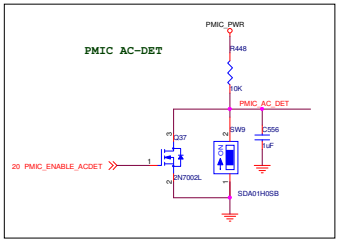
Input Capacitor for power rails - Place near U5 pins 1, 43, 37,12

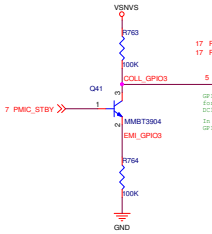
Place C546 near Pin 5

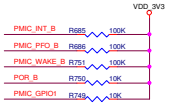
Place C568 near Pin 36

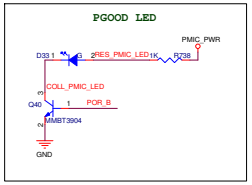




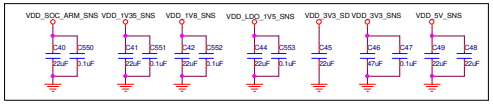


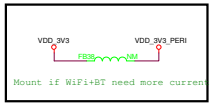


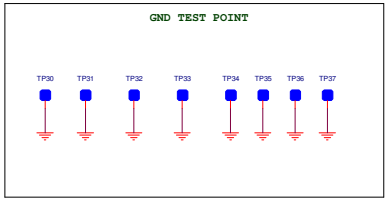


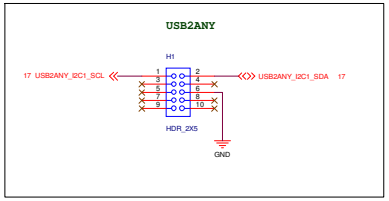


Output Capacitor for all the power rails - Place near the output Inductor

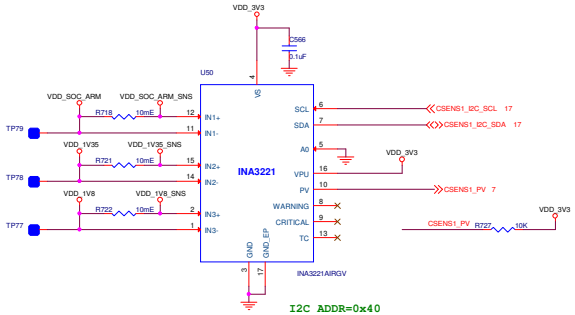


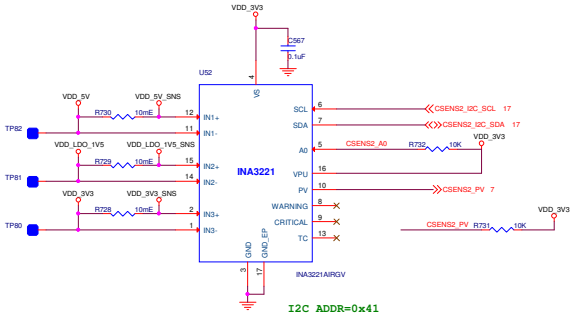






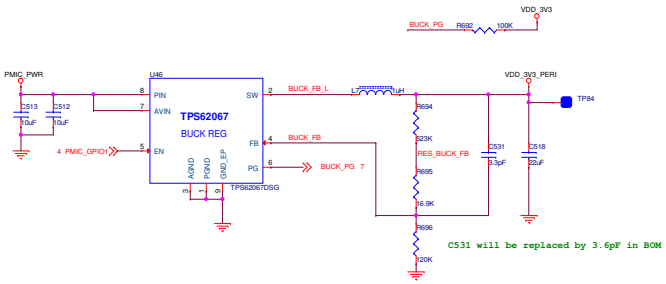
CURRENT AND VOLTAGE MONITORING



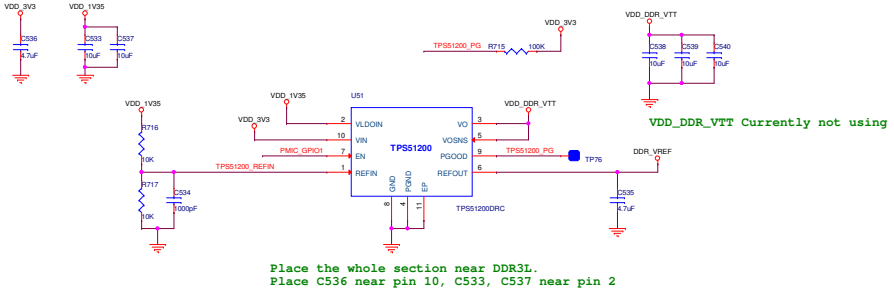


VVDN TECHNOLOGIES	A2	Title : PMIC	
	Fab No : 501-1-00947		Rev: B1
	Asy No : 701-1-01125	Sheet 4 of 21	

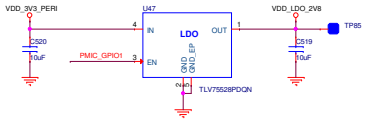
PERIPHERAL 3V3



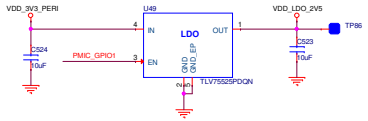
DDR3L VREF



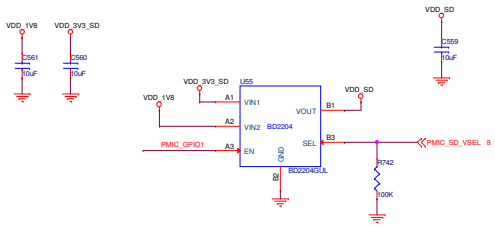
2V8 LDO



2V5 LDO



SD CARD VOLTAGE SELECT



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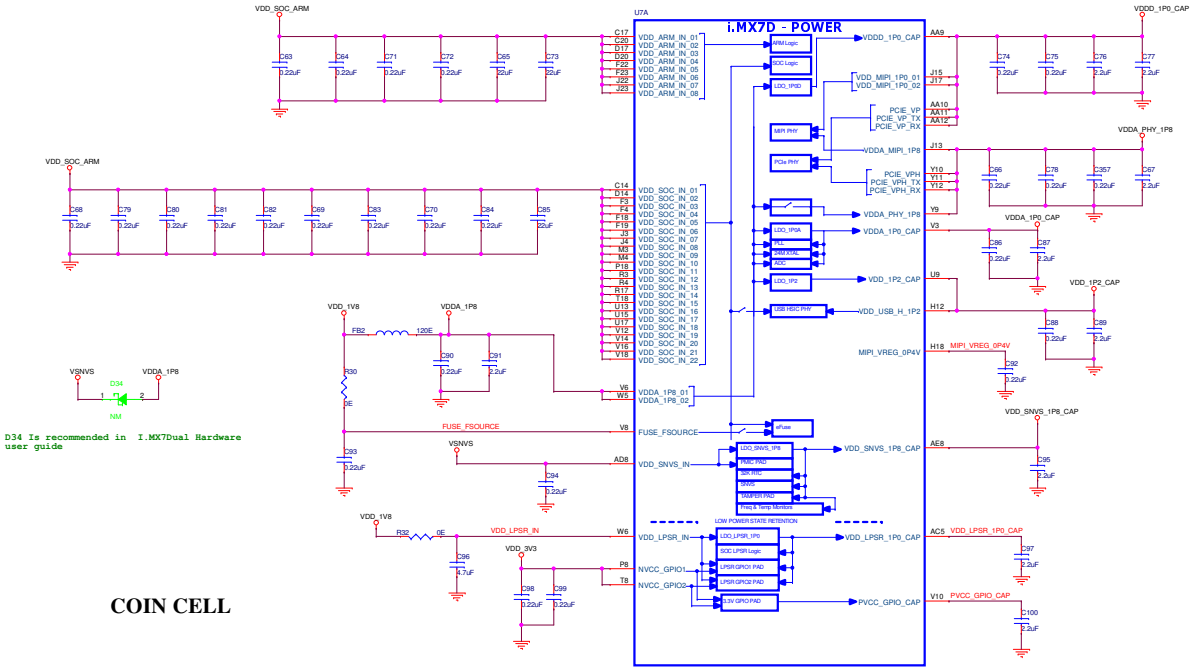
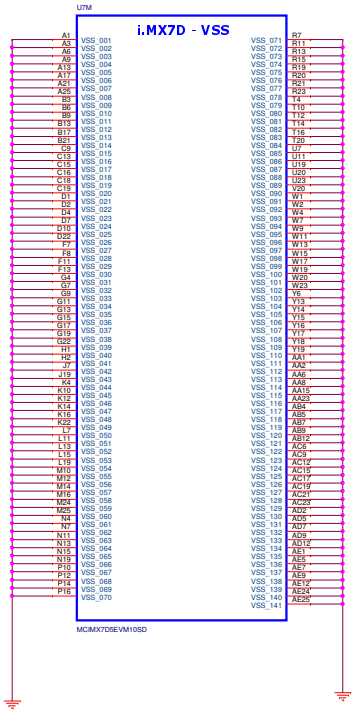
VVDN TECHNOLOGIES	A2	Title : POWER DC-DC
	Fab No : 501-1-00947	Rev: B1
	Asy No : 701-1-01125	Sheet 5 of 21

CPU POWER





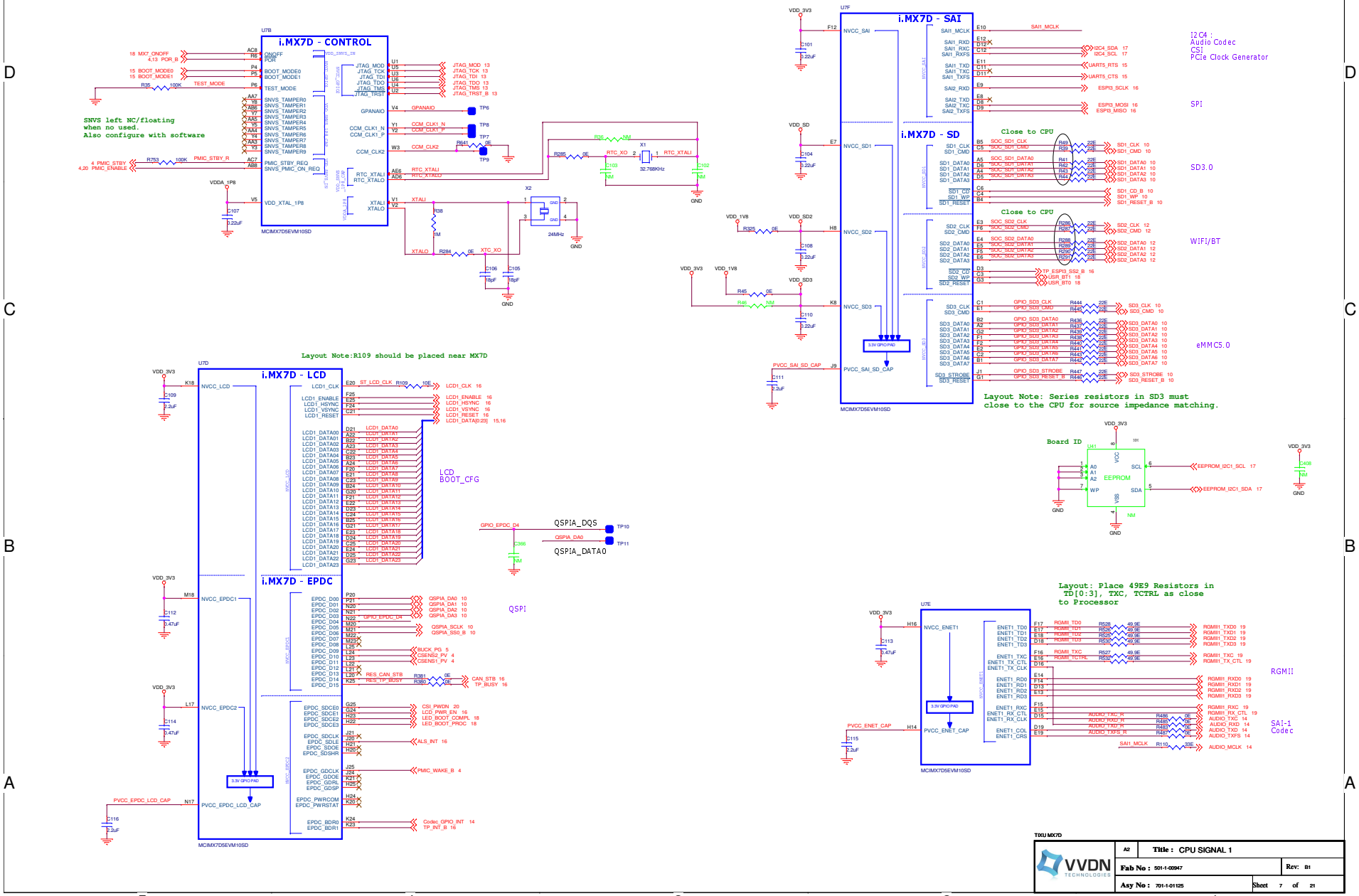
D34 Is recommended in I.MX7Dual Hardware user guide

COIN CELL

Place COIN CELL near AD8 of U7

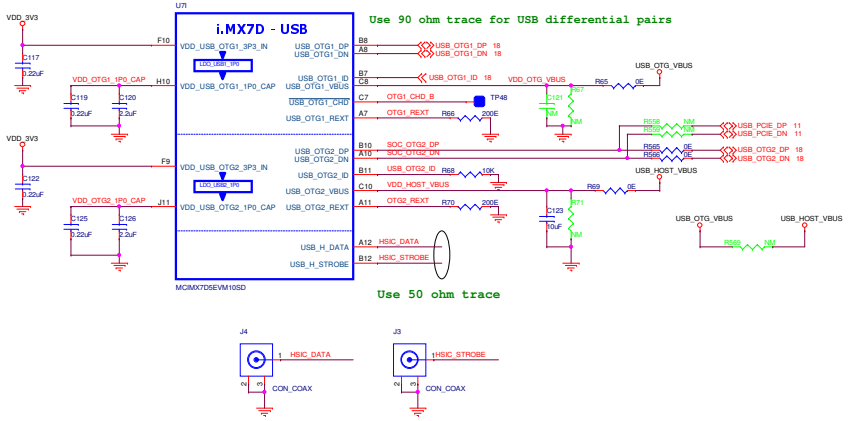
TXU MX7D	A2	Title : CPU POWER	
VVDN TECHNOLOGIES	Fab No : 501-1-00947		Rev: B1
	Asy No : 701-1-01125		Sheet 6 of 21

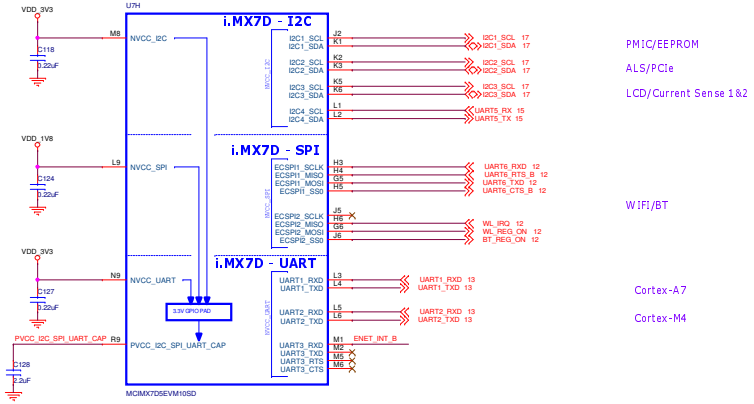
CPU SIGNAL 1

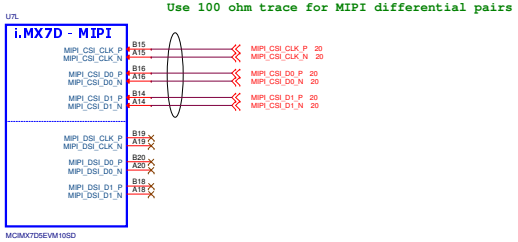


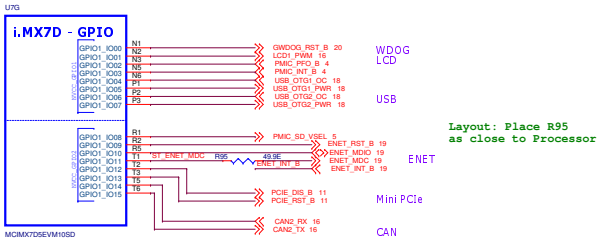
TXU MX7D	A2	Title : CPU SIGNAL 1	
VVDN TECHNOLOGIES	Fab No : 501-1-00947		Rev: B1
	Asy No : 701-1-01125	Sheet 7 of 21	

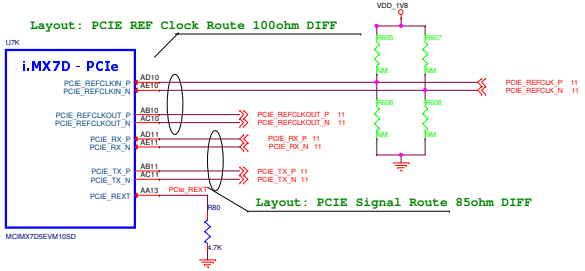
CPU SIGNAL 2

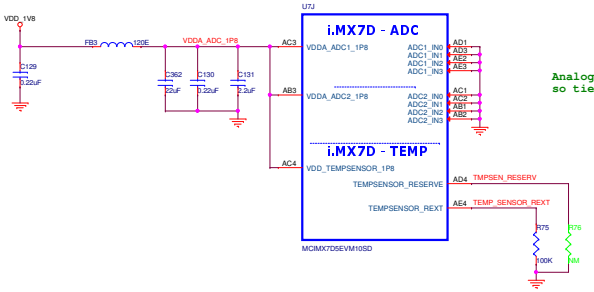






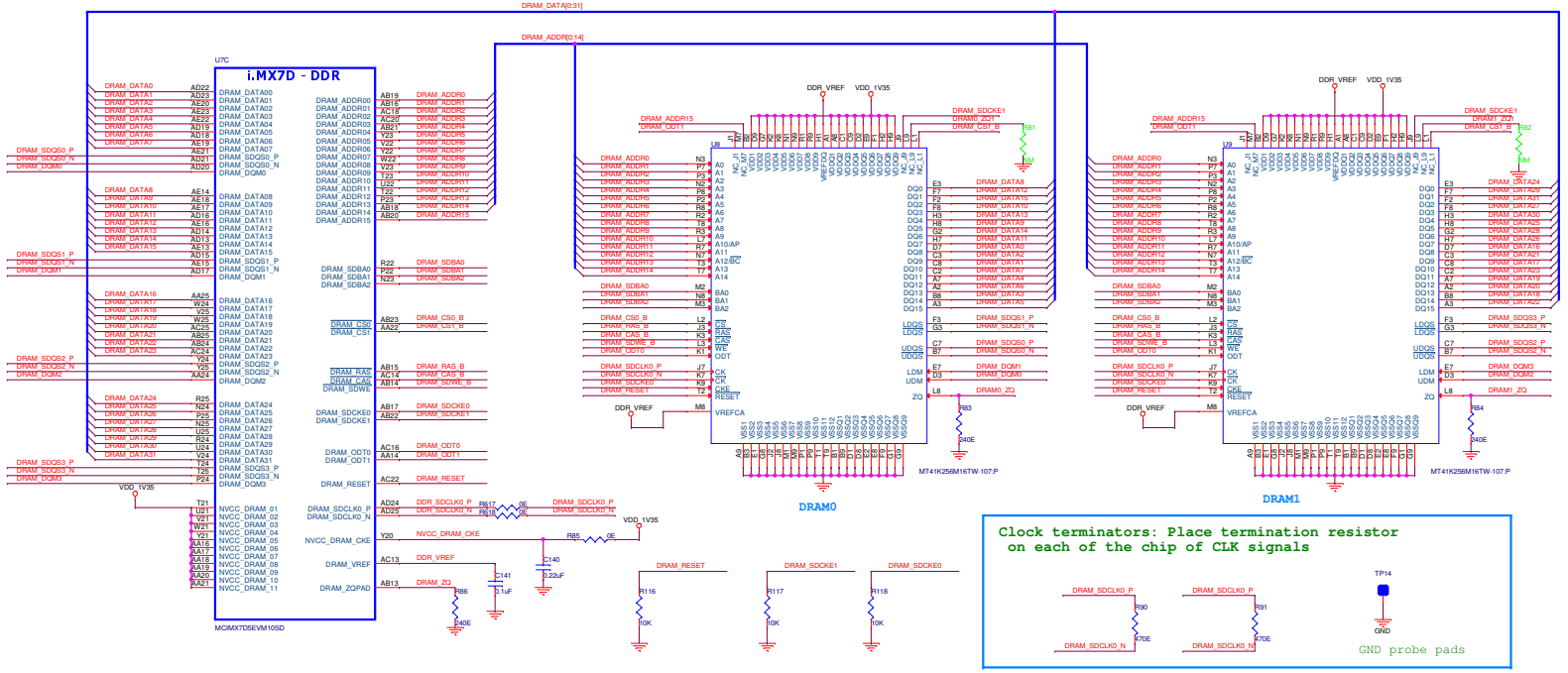


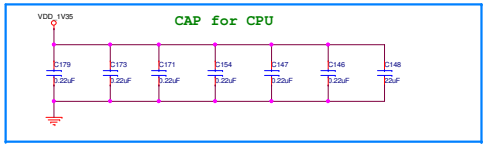


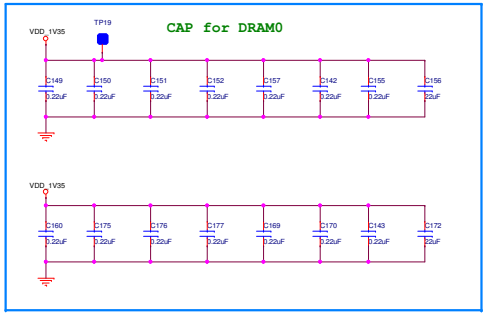


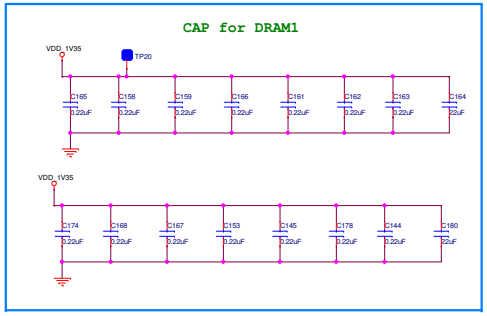
TXU MX7D	A2	Title : CPU SIGNAL 2	
VVDN TECHNOLOGIES	Fab No : 501-1-00947		Rev: B1
	Asy No : 701-1-01125		Sheet 8 of 21

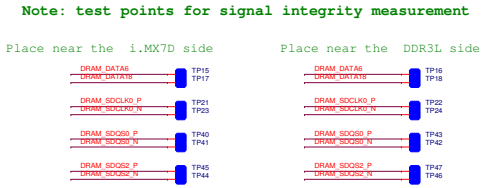
DDR3L

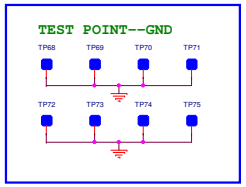












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VVDN TECHNOLOGIES	A2	Title : DDR3L
	Fab No : 501-1-00947	Rev: B1
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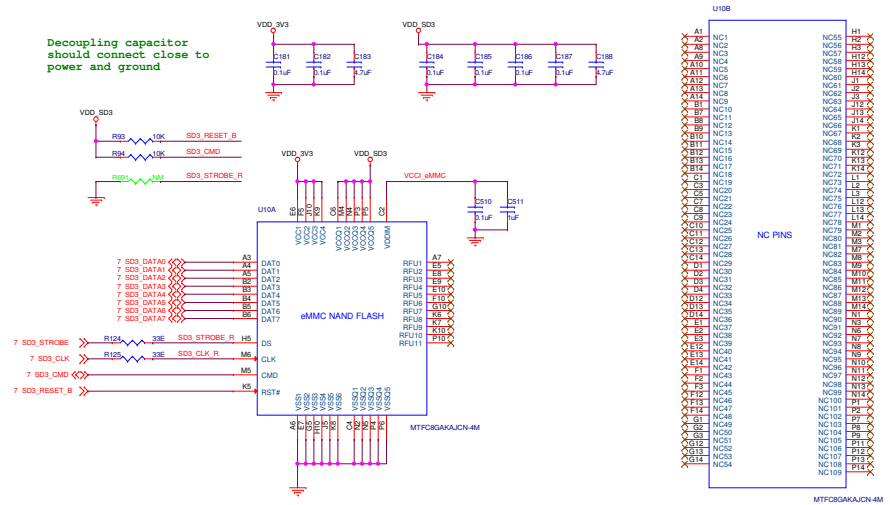
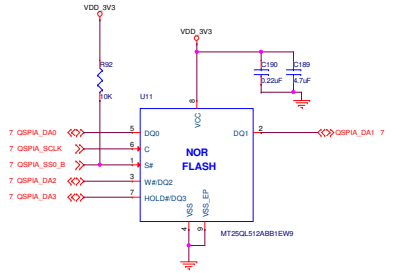
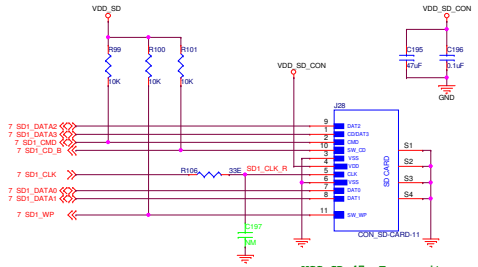
eMMC 5.0

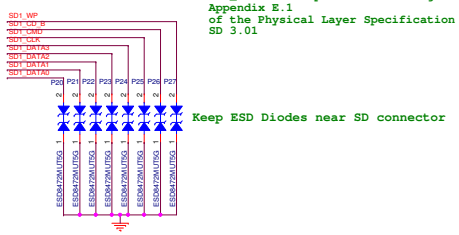


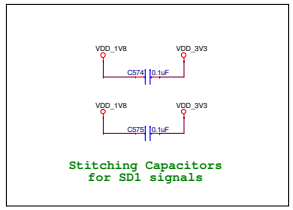
QSPI NOR FLASH

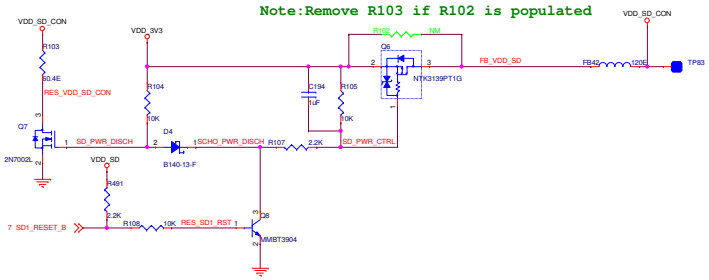


SD CARD



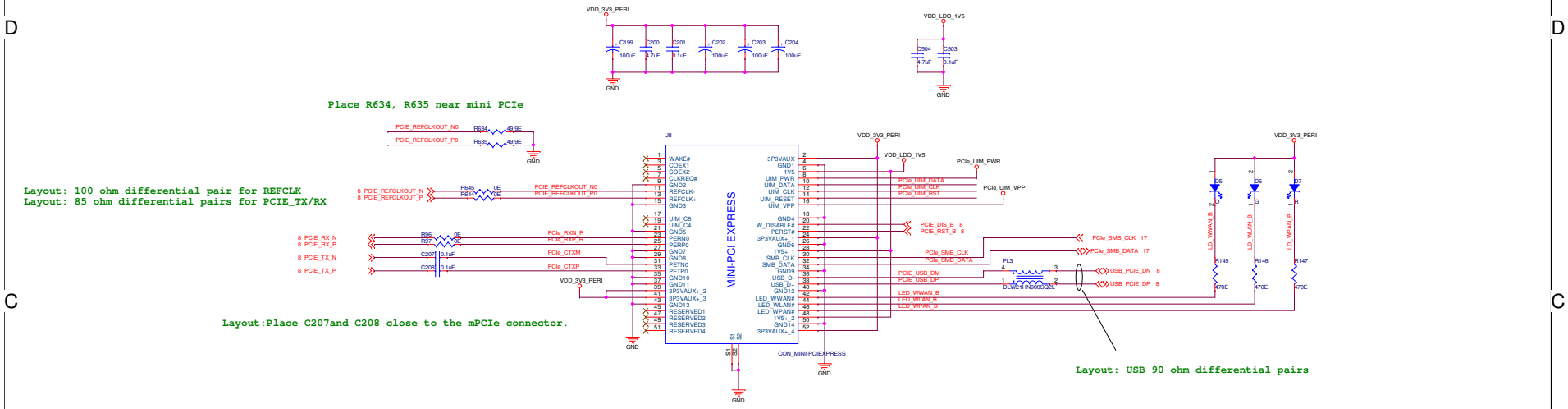




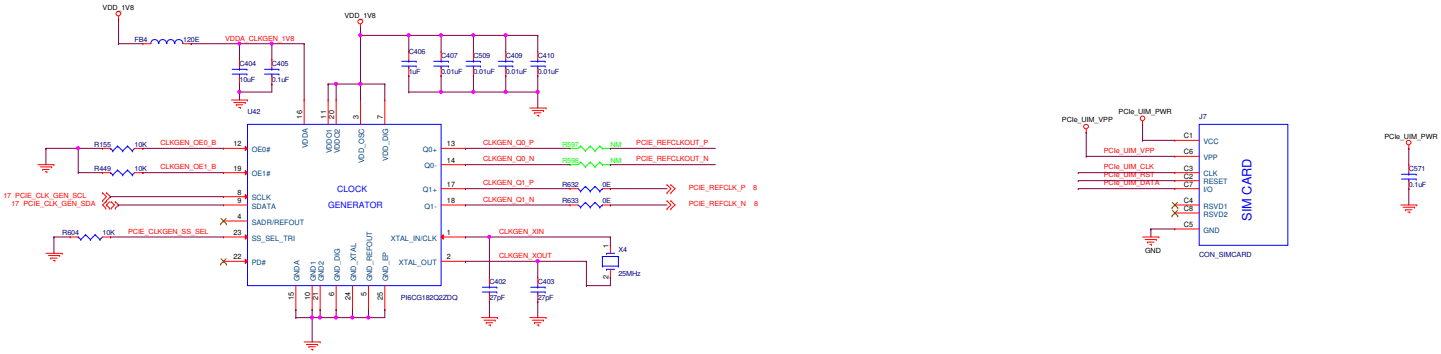


TIXU MX7D	A2	Title : eMMC/FLASH/SD	
VVDN TECHNOLOGIES	Fab No : 501-1-00947		Rev: B1
	Asy No : 701-1-01125		Sheet 10 of 21

Mini-PCIE



NOTE:
This design assumes a normal loading on the VDD_3V3_PERI rail of up to 1A.
The VDD_LDO_1V5 rail is allowed a maximum of 250 mA.



VVDN TECHNOLOGIES	A2	Title : mini_PCIe
	Fab No : 501-1-00947	Rev: B1
	Asy No : 701-1-01125	Sheet 11 of 21

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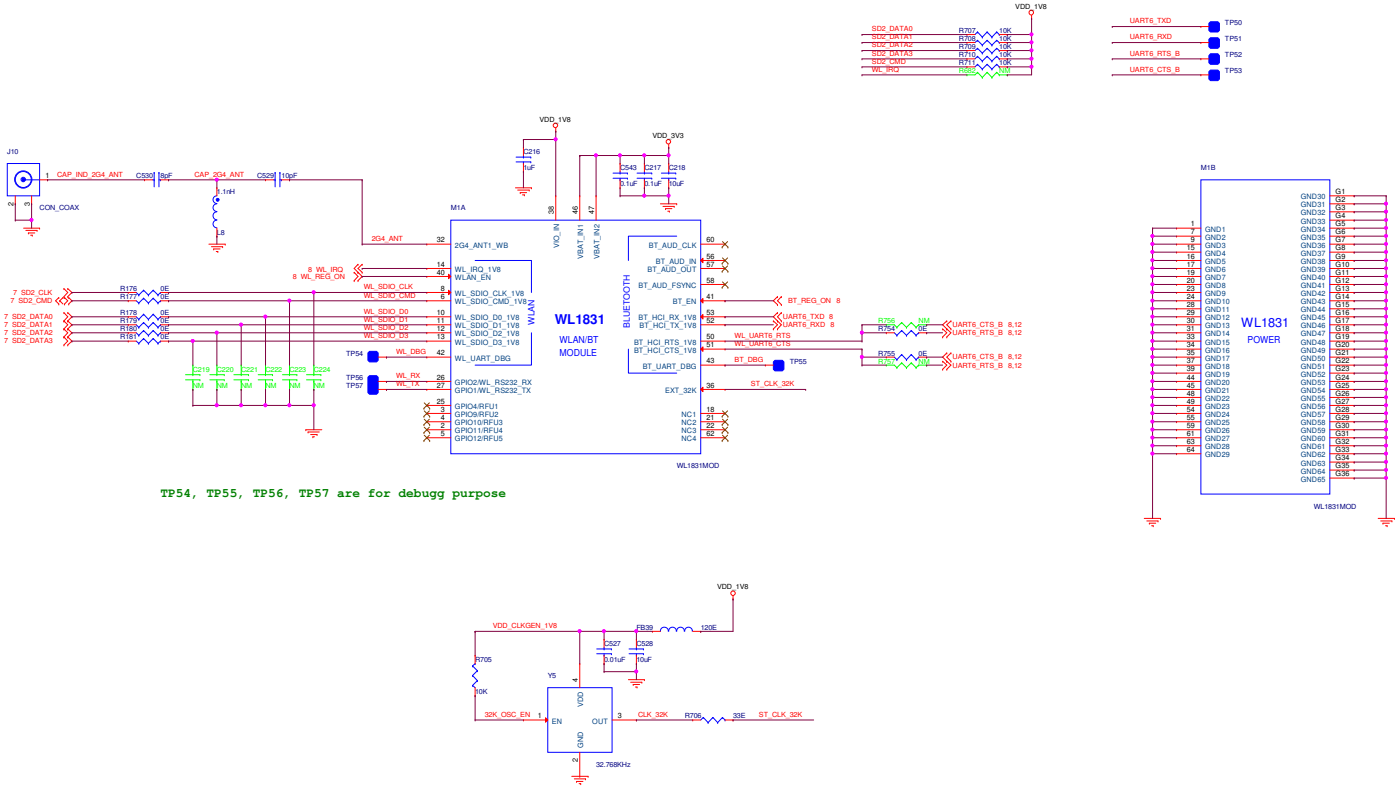
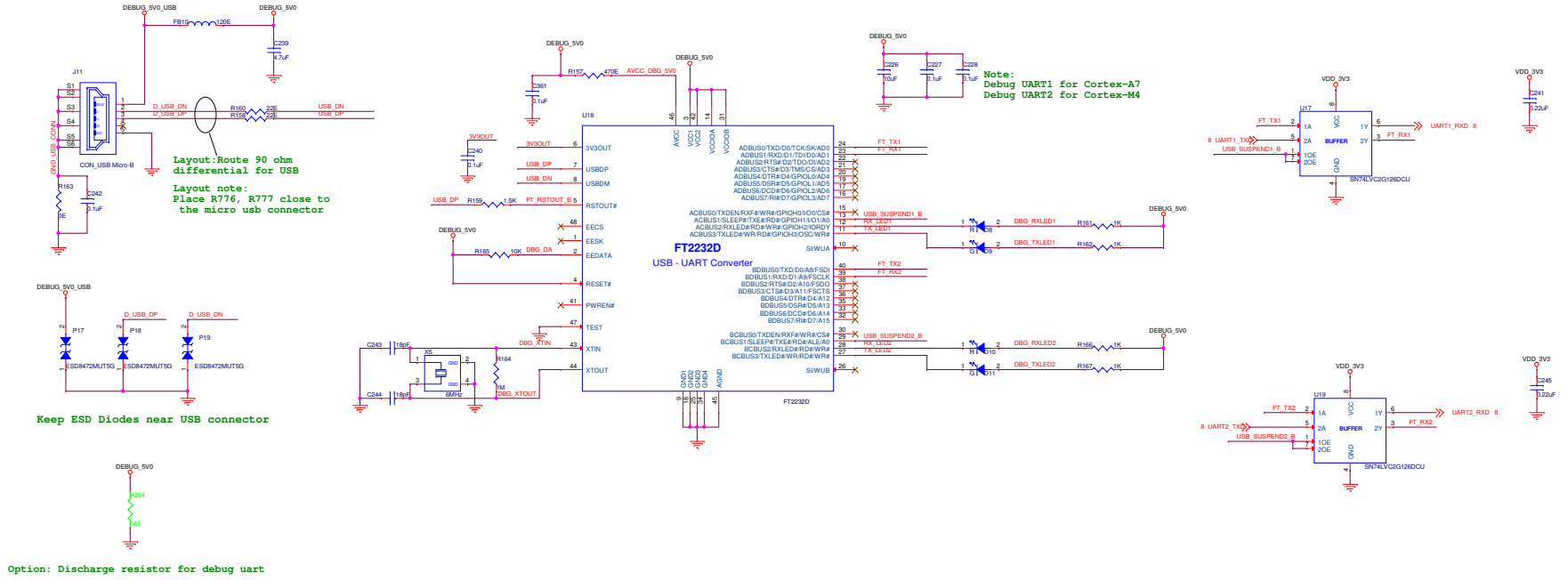
WiFi/BT



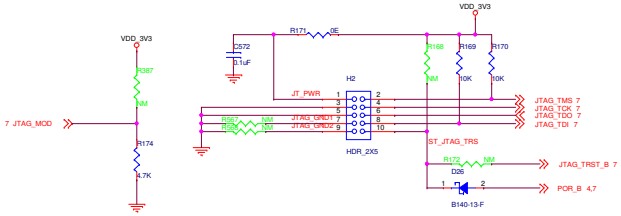
TIXU MX7D

VVDN TECHNOLOGIES	A2	Title : WiFi/BT
	Fab No : 501-1-00947	Rev: B1
	Asy No : 701-1-01125	Sheet 12 of 21

DEBUG UART

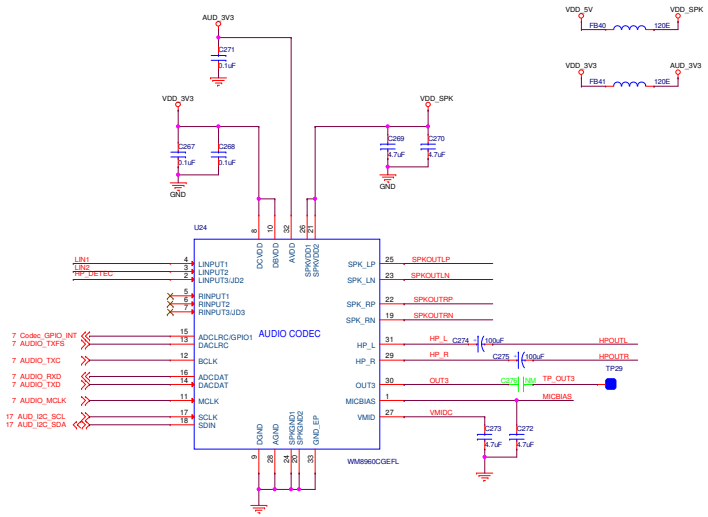


JTAG

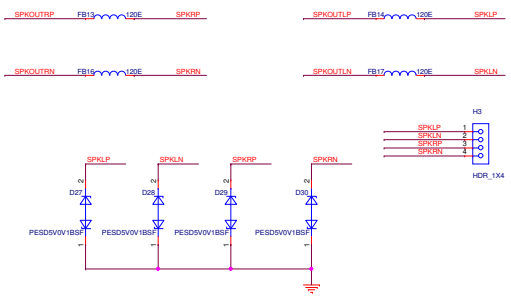


TIXU MX7D	A2	Title : DEBUG UART/JTAG	
VVDN TECHNOLOGIES	Fab No : 501-1-00947		Rev: B1
	Asy No : 701-1-01125	Sheet 13 of 21	

AUDIO

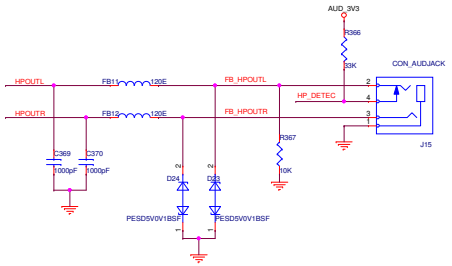


Speaker Out



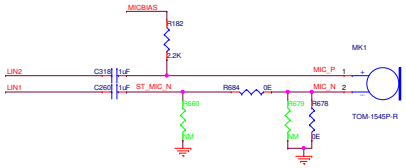
Keep ESD Diodes near SPK connector

HP OUT



Keep ESD Diodes near Headphone connector

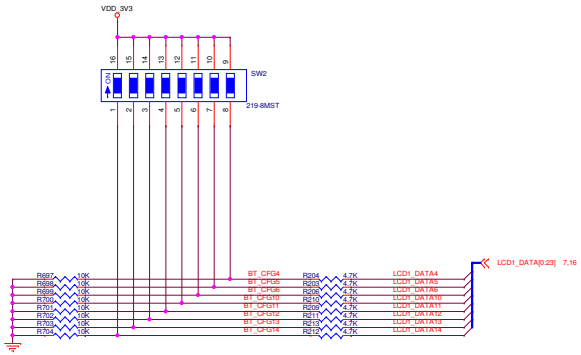
MIC INPUT



TIXU MX7D

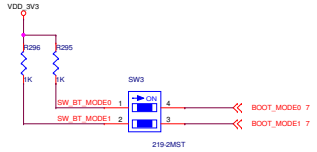
VVDN TECHNOLOGIES	A2	Title : AUDIO
	Fab No : 501-I-00947	Rev: B1
	Asy No : 701-I-01125	Sheet 14 of 21

BOOT CONFIG



BOOT MODE

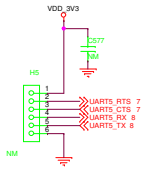
BOOT_MODE[1:0]	Boot type
00	Boot From Fuses
01	Serial Downloader
10	Internal Boot
11	Reserved



BOOT TABLE – SW2

1	2	3	4	5	6	7	8
BT_CFG[14]	BT_CFG[13]	BT_CFG[12]	BT_CFG[11]	BT_CFG[10]	BT_CFG[6]	BT_CFG[5]	BT_CFG[4]
001 = SD/eSD Boot			Port Select: 00 - eSDHC1 01 - eSDHC2 10 - eSDHC3		0	0	Bus Width: 0 - 1-bit 1 - 4-bit
010 = MMC/eMMC Boot					Bus Width: 000 - 1-bit 001 - 4-bit 010 - 8-bit 101 - 4-bit DDR (MMC 4.4) 110 - 8-bit DDR (MMC 4.4)		
100 = QSPI Boot			0	0	0	0	0

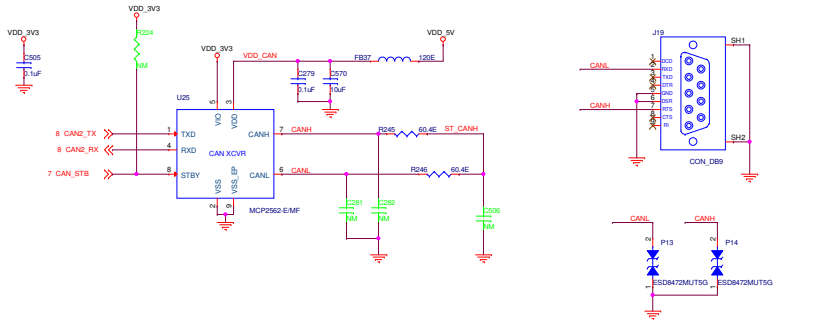
UART HEADER



TIXU MX7D

VVDN TECHNOLOGIES	A2	Title : BOOT/UART HEADER
	Fab No : 501-1-00947	Rev: B1
	Asy No : 701-1-01125	Sheet 15 of 21

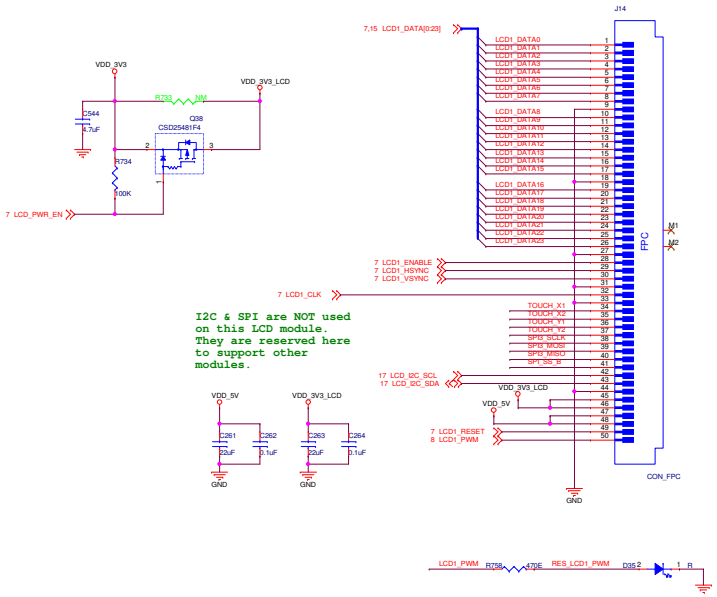
CAN



Keep ESD Diodes near CAN connector

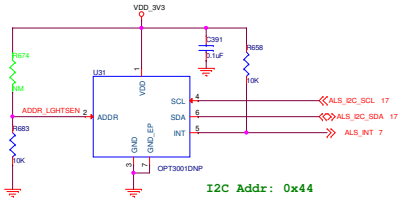
LCD

ADAFRUIT LCD



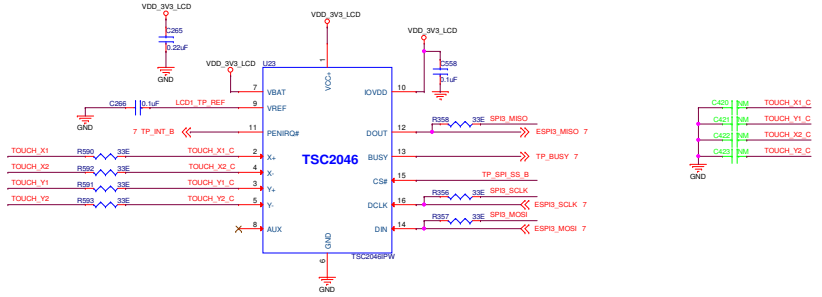
I2C & SPI are NOT used on this LCD module. They are reserved here to support other modules.

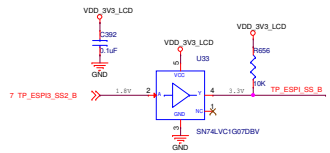
Ambient Light Sensor

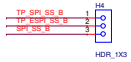


I2C Addr: 0x44

Place C265 near VBAT



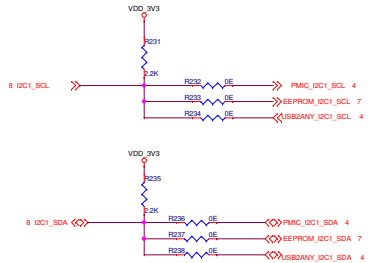




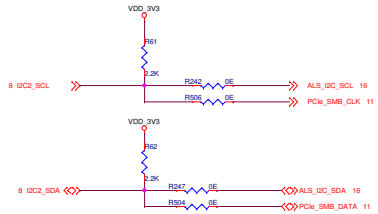
TIXU MX7D

VVDN TECHNOLOGIES	A2	Title : CAN,LCD/ALS
	Fab No : 501-1-00947	Rev: B1
	Asy No : 701-1-01125	Sheet 16 of 21

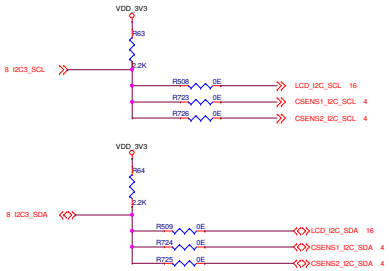
I2C1



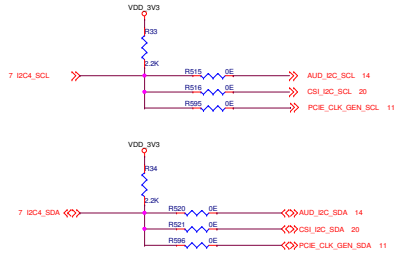
I2C2



I2C3



I2C4

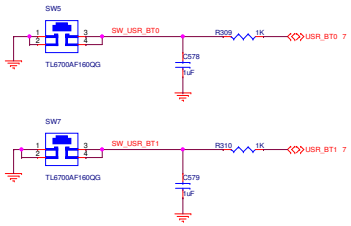


T8XU MX7D

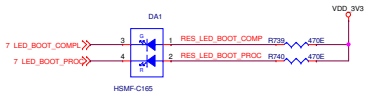
VVDN TECHNOLOGIES

A2	Title : I2C	
Fab No : 501-1-00947		Rev: B1
Asy No : 701-1-01125		Sheet 17 of 21

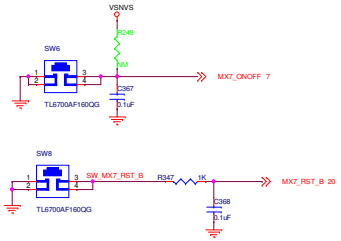
User Button



Status LED

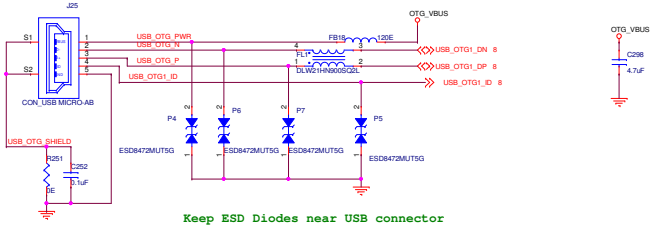


Power Button



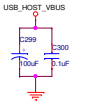
USB OTG

Layout: USB 90 ohm differential pairs

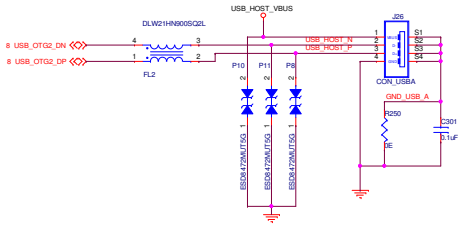


Keep ESD Diodes near USB connector

USB HOST

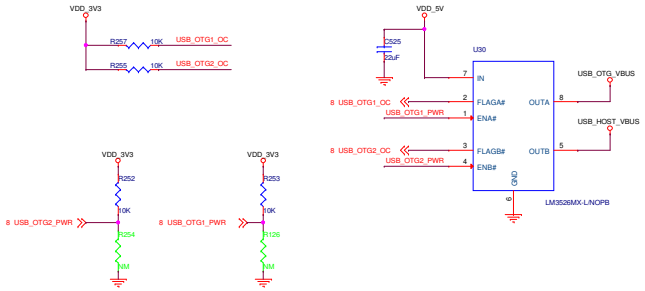


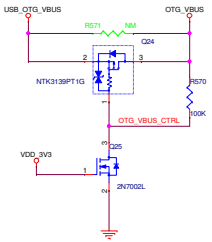
Layout: USB 90 ohm differential pairs



Keep ESD Diodes near USB connector

USB Power

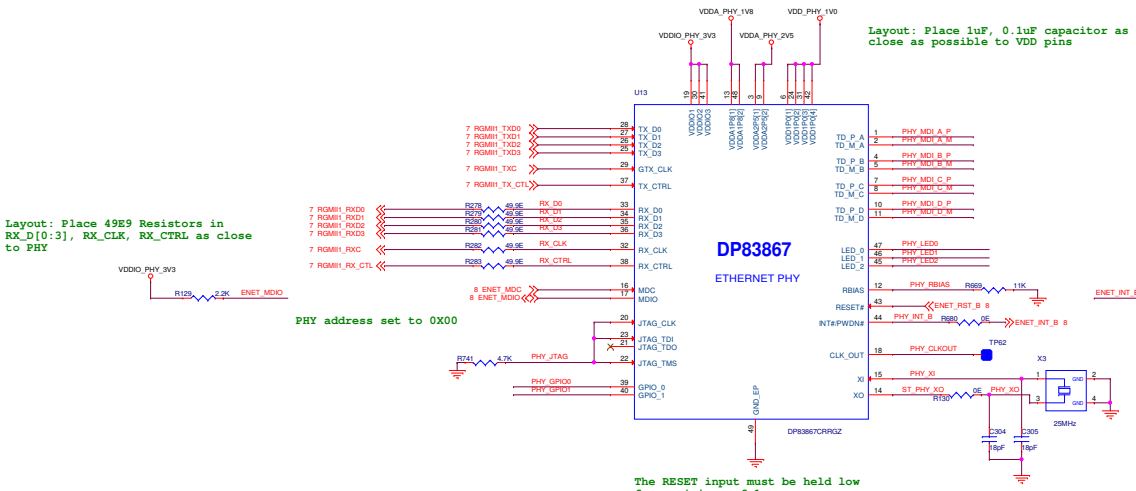


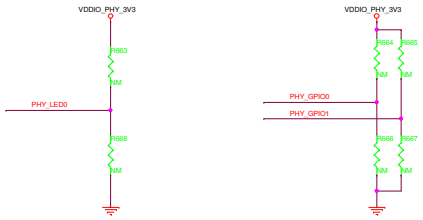


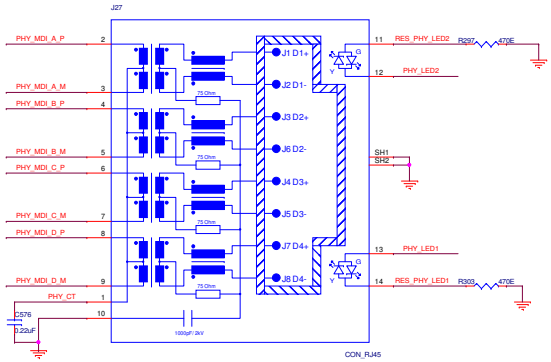
TIXU MX7D

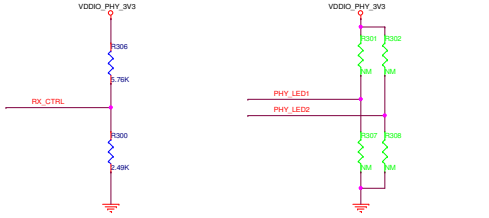
VVDN TECHNOLOGIES	A2	Title : USB/BUTTON
	Fab No : 501-1-00947	Rev: B1
	Asy No : 701-1-01125	Sheet 18 of 21

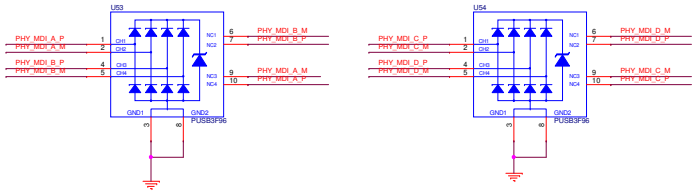
ETHERNET PHY







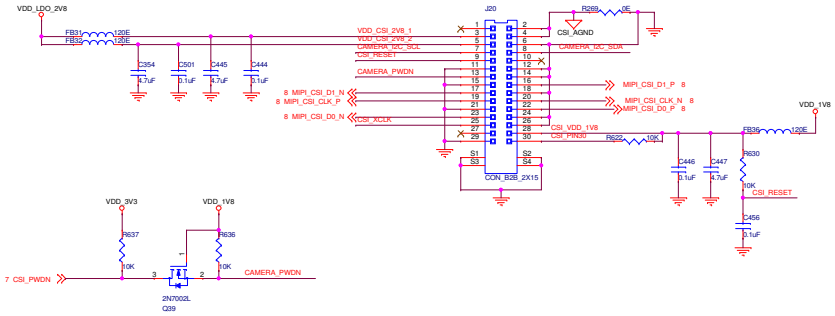


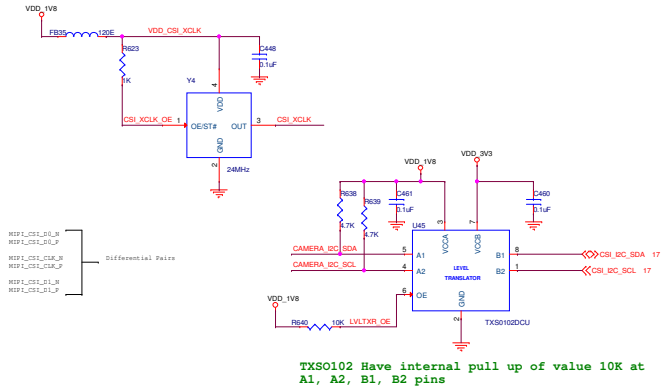


All path length from P2, P3 should be kept small to minimize parasitic inductance. Also place near the connector J27

TIXU MX7D	A2	Title : ETHERNET
VVDN TECHNOLOGIES	Fab No : 501-1-00947	Rev: B1
	Asy No : 701-1-01125	Sheet 19 of 21

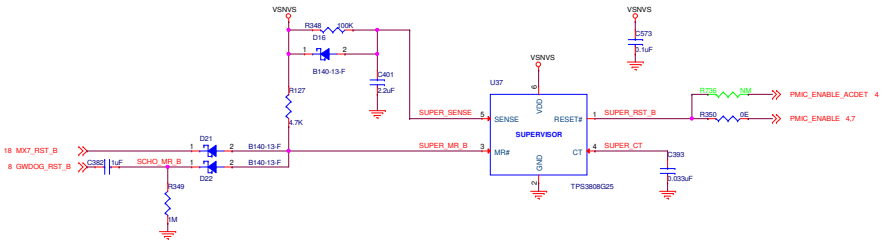
CSI





TXS0102 Have internal pull up of value 10K at A1, A2, B1, B2 pins

WATCH DOG

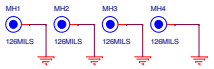


TIXU MX7D

VVDN TECHNOLOGIES	A2	Title : CSI/WATCHOG/IO
	Fab No : 501-1-00947	Rev: B1
	Asy No : 701-1-01125	Sheet 20 of 21

MISCELLANEOUS

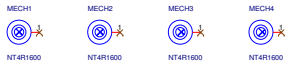
MOUNTING HOLES



GLOBAL FIDUCIALS

LOCAL FIDUCIALS

MINI PCIe HANDOFF



T0U MX7D

VVDN TECHNOLOGIES	A2	Title : MISCELLANEOUS
	Fab No : 501-1-00947	Rev: B1
	Asy No : 701-1-01125	Sheet 21 of 21

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